T-P-DUAL SERIES – VOID FILLER WITH ELECTRICALLY INSULATING CARRIER (0.50 – 5.00MM)

EMI THERMAL

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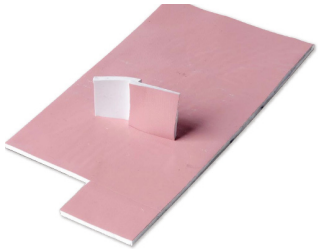
DATASHEET



FEATURES

- Ultra-Soft with High conformability
- Thermal Void Filler with an Electrically Insulating Carrier
- Resistant to Cut-Through / Punctures
- 1.0 W/mK Thermal Conductivity
- Low Thermal Impedance
- Naturally Tacky

APPLICATIONS

- Electronic Components: IC, CPU, MOS
- LED, Motherboards, Power Supplies, Heat Sinks, LCD-TV, Notebook PC, PC
- Telecom Devices, Wireless Hub, Automotive and Aerospace applications

PROPERTIES	TEST METHOD	UNIT	T-P-DUAL SERIES
Material	-	-	Ceramic filled silicon elastomer
Colour	Visual	-	White and Pink
Thickness (±10%) Increments of 0.25mm/0.01inch	-	-	0.5-5.00 0.02-0.20
Thermal Conductivity	ASTM-D5470	W/mK	1.0
Hardness (±10)	ASTM-D2240	Shore 00	00 20
Flammability Rating	UL94	-	V0
Breakdown Voltage (1.0mm)	ASTM-D149	kV	≥10
Specific Gravity	-	g/cm^3	2.3
Working Temperature	-	°C	-40 - 200
Volume Resistance	ASTM-D257	Ohm-cm	10^{12}

THERMAL IMPEDANCE (4MM/SHORE 00 20)

Deflection Rate (%)	10	20	30
Thermal Impedance (°C-in²/W)	4.71	4.28	3.85

NOTES

- Customised shapes are available
- The above performance data is tested in an environment of 70% humidity, temperature 25 °C
- This data is intended for reference purposes only. It is recommended that the material is tested to fully evaluate its performance ensuring it is fit for purpose.

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